2SK2460N

Features

- 1) Low on-resistance.
- 2) High-speed switching.
- 3) Wide SOA (safe operating area).
- 4) Gate-source voltage guaranteed at $V_{\text{GSS}} = \pm 30V$.

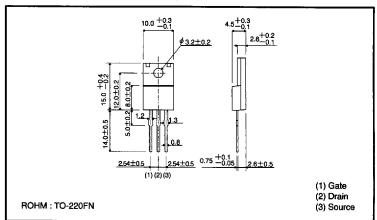
Switching (250V, 5A)

- 5) Easily designed drive circuits.
- 6) Easy to use in parallel.

Structure

Silicon N-channel MOSFET transistor

External dimensions (Units: mm)



●Absolute maximum ratings (Ta = 25°C)

Parameter		Symbol	Limits	Unit
Drain-source voltage		V _{DSS}	250	٧
Gate-source voltage		V _{GSS}	±30	٧
Drain current	Continuous	lo	5	Α
	Pulsed	lpp*	20	Α
Drain reverse current	Continuous	IDR	5	Α
	Pulsed	IDRP*	20	Α
Total power dissipation(Tc=25°C)		Po	30	W
Channel temperature		Tch	150	Ç
Storage temperature		Tstg	-55~150	Ç

* Pw≤10 μs, Duty cycle≤1%

Packaging specifications

Туре	Package	Bulk
	Code	
	Basic ordering unit (pieces)	500
2SK2460N		0

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●Electrical characteristics (Ta = 25℃)

Parameter	Symbol	Min.	Тур.	Мах.	Unit	Conditions
Gate leakage current	lgss	_	_	±100	n A	V _{GS} =±30V, V _{DS} =0V
Drain-source breakdown voltage	V(BR)DSS	250	_	_	٧	In=1mA, Vgs=0V
Drain cutoff current	loss	_	_	100	μΑ	V _{DS} =250V, V _{GS} =0V
Gate threshold voltage	VGS(th)	2	_	4	٧	V _{DS} =10V, I _D =1mA
Drain-source on-state resistance	RDS(on)		0.55	0.75	Ω	In=2.5A, Vgs=10V
Forward propagation admittance	Yts	2	3.5		s	V _{DS} =10V, I _D =2.5A
Input capacitance	Ciss	_	500	_	рF	V _{DS} =10V
Output capacitance	Coss	_	150		рF	V _{GS} =0
Reverse transfer capacitance	Crss	_	35	_	рF	f=1MHz
Turn-on delay time	td(on)	_	7	_	ns	lo=2.5A, Voo≒100V
Rise time	tr		15		ns	V _{GS} =10V
Turn-off delay time	ta(off)	_	30	_	ns	RL=40 Ω
Fall time	tı	-	25	_	ns	R _G =10Ω
Reverse recovery time	t _{rr}	_	150	_	ns	IDR=5A, VGS=0V
Reverse recovery load	Qm		0.7	_	μC	di/dt=100A/ μs

●Electrical characteristic curves

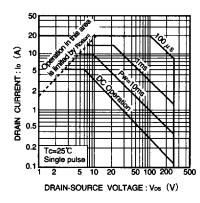


Fig.1 Maximum Safe Operating Area

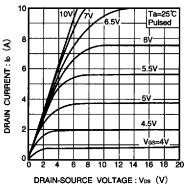


Fig.2 Typical Output Characteristics

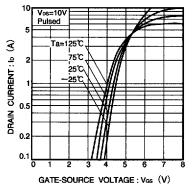


Fig.3 Typical Transfer Characteristics

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Electrical characteristic curves

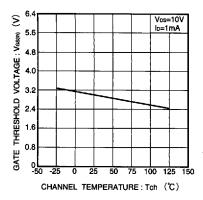
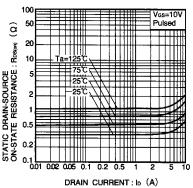
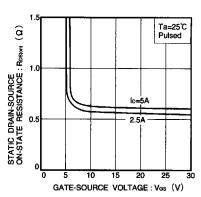


Fig.4 Gate Threshold Voltage vs. Channel Temperature



Static Drain-Source On-Resistance vs. Drain Current



Static Drain-Source Fig.6 On-State Resistance vs. Gate-Source Voltage

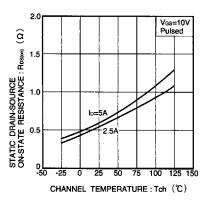
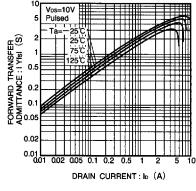


Fig.7 Static Drain-Source On-State Resistance vs. Channel Temperature



Forward Transfer Admittance vs. Drain Current

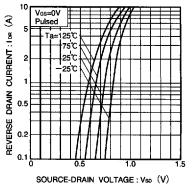


Fig.9 Reverse Drain Current vs. Source-Drain Voltage (I)

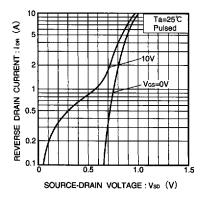


Fig.10 Reverse Drain Current vs. Source-Drain Voltage (II)

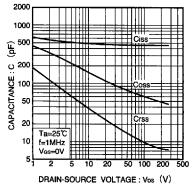
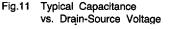
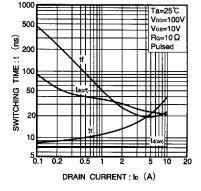


Fig.11 Typical Capacitance





Switching Characteristics (See Figure, 16 and 17 for measurement circuits)

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Electrical characteristic curves

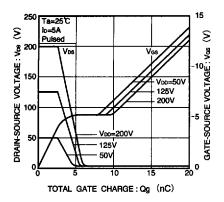


Fig.13 Dynamic Input Characteristics (See Figure. 18 for measurement circuit)

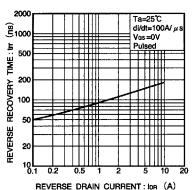


Fig.14 Rverse Recovery Time vs. Reverse Drain Current

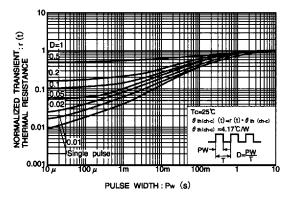


Fig.15 Normalized Transient Thermal Resistance Vs. Pulse Width

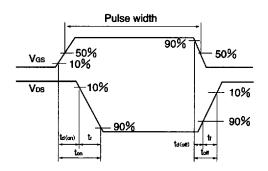


Fig.17 Switching Time Waveforms

Switching characteristics measurement circuit

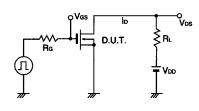


Fig.16 Switching Time Measurement Circuit

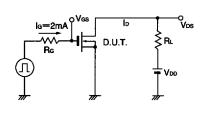
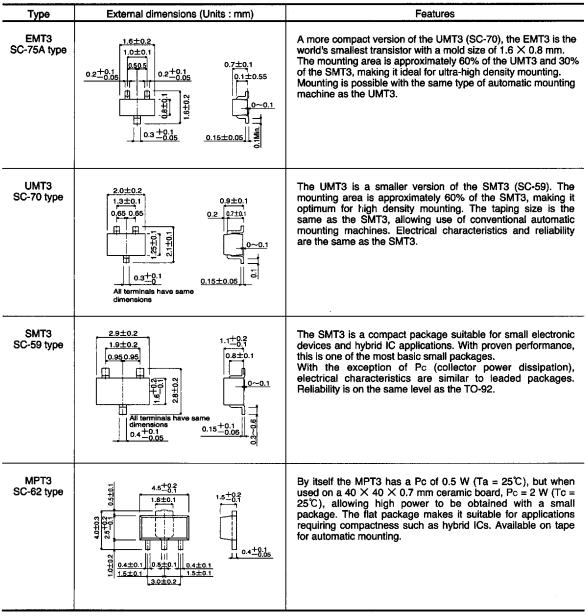


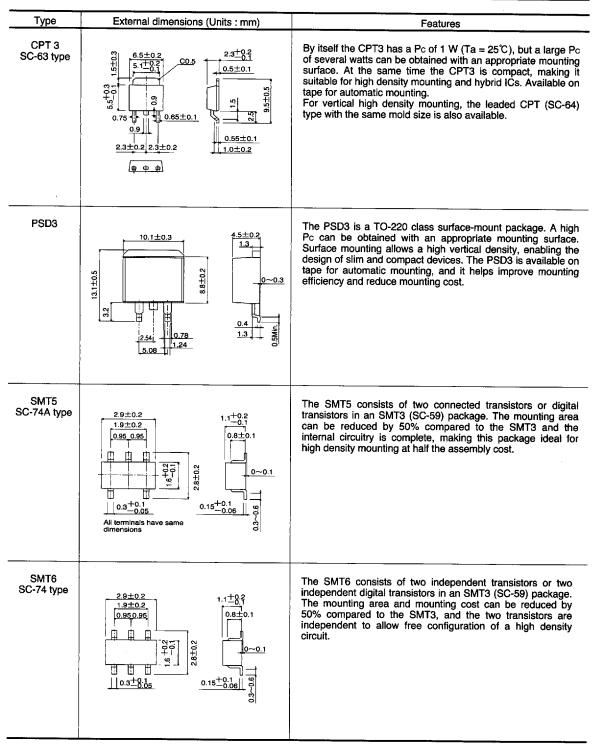
Fig.18 Gate Charge Measurement Circuit

Packages

ROHM has been manufacturing transistors since 1975. In the development of products, we constantly strive to anticipate the needs of our customers. Regarding packages, the demands of the market for compactness, low power consumption, low power dissipation and automatic mounting support are becoming ever greater, and we are strengthening our product development system to meet these needs.

Types and features of surface-mount packages

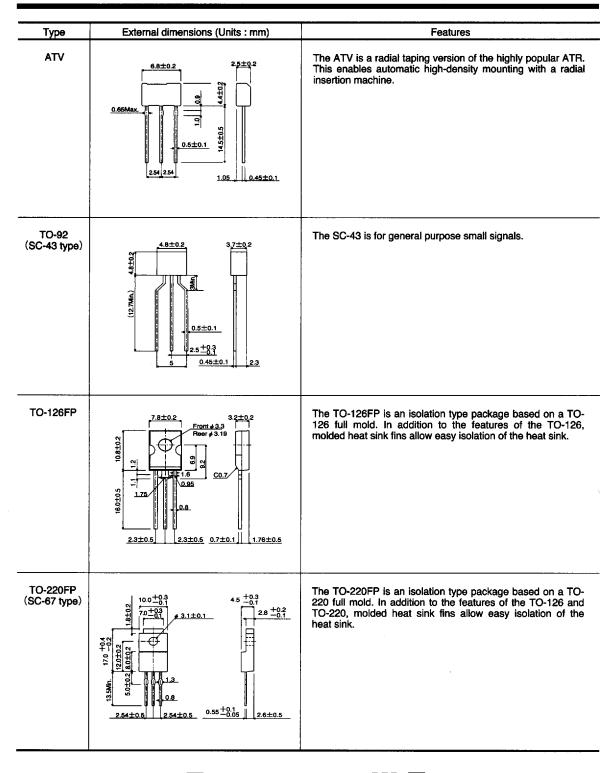




Туре	External dimensions (Units : mm)	Features
UMT5 SC-88A type	2.0±0.2 1,3±0.1 0,85 0,85 0,7 0,005 All terminals have same dimensions	The UMT5 consists of two connected transistors or digital transistors in a UMT3 (SC-70) package. The mounting area can be reduced by 50% compared to the UMT3 and the internal circuitry is completed, making this package ideal for high density mounting at half the assembly cost.
UMT6 SC-88 type	2.0±0.2 1,3±0.1 0.65 0.65 0.7 0.7 0.7 0.7 0.7 0.7 0.7 0.7	The UMT6 consists of two independent transistors or two independent digital transistors in a UMT (SC-70) package. The mounting area and mounting cost can be reduced by 50% compared to the UMT3, and the two transistors are independent to allow free configuration of a high density circuit.

●Types and features of leaded packages

Туре	External dimensions (Units : mm)	Features
SPT (SC-72 type)	2±0,2 0.45±0.15 0.45±0.15 0.5 0.45±0.15 0.5 0.45±0.15	The SPT is a smaller version of the conventional TO-92 type. The body size (3×4×2 mm³) has been reduced to 1/4 that of the TO-92 (5×5×4 mm³). The SPT is available on tape for automatic insertion, and less space is occupied on the printed circuit board than the TO-92. Reliability is the same as the TO-92.
FTR	0.65±0.1 2.4±0.2 0.55±0.1 0.55±0.1 0.45±0.1 0.45±0.1	SIL type with a height of 3.4 mm and a lead pitch of 2.54 mm.
FTL	0.65Max 2.4±0.2 0.65Max 2.4±0.2 0.5±0.1 0.5±0.1	The FTL is a radial taping version of the highly popular FTR. This enables automatic high-density mounting with a radial insertion machine.
ATR (SC-71 type)	0.65Max	SC-71type with a height of 4.4 mm and a Pc=1W type.



Type	External dimensions (Units : mm)	Features
TO-220FN	\$3.2±0.2	The TO-220FN features the same performance as the TO-220FP with approximately 2 mm less height, allowing the design of slimmer devices. Furthermore, the elimination of support pins in the fin (collector electrode) solves short-circuiting problems with neighboring components and the chassis. To make the height to the installation hole the same as the TO-220FP, it can be replaced as is from the TO-220FP.